

ABSTRACT

A heat dissipation module for a CPU has a heat dissipation device, a fan fixing frame, and a fan. The fan fixing frame can be fixed above the heat dissipation device. The fan fixing frame has a top plate, two side plates, a plurality of the elastic pressing components and at least one positioning elastic strip. The two side plates extend to form a pulling portion and a plurality of clipping portions. The elastic pressing components are installed on the top plate, the positioning elastic strip being installed on the top plate, and the positioning elastic trip forming at least two pushing portions to touch the outer surface of the two side plates. The fan is fixed on the top plate of the fan fixing frame. Some extra useful structures establish an easy to assemble and disassemble module with good related properties.